



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

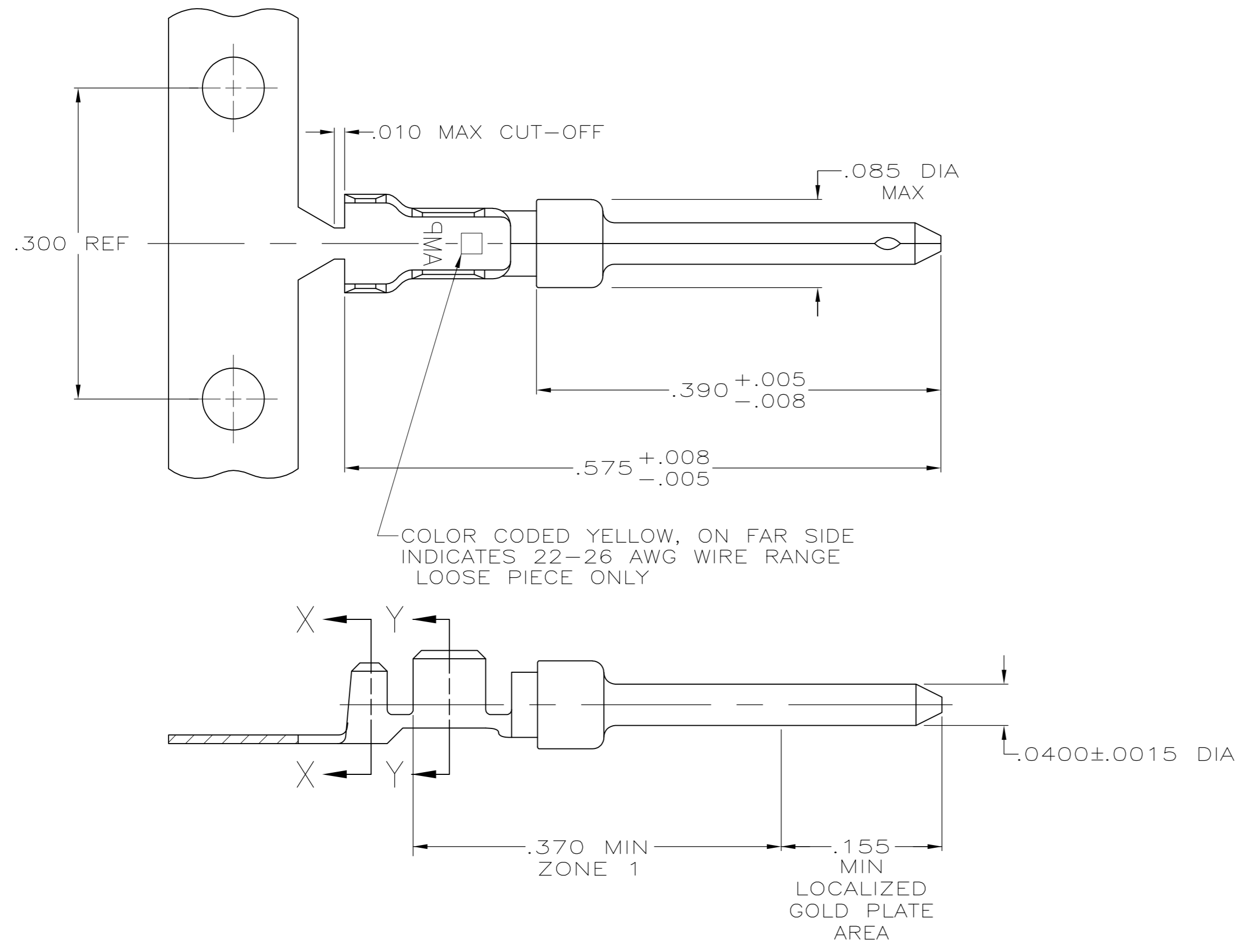
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

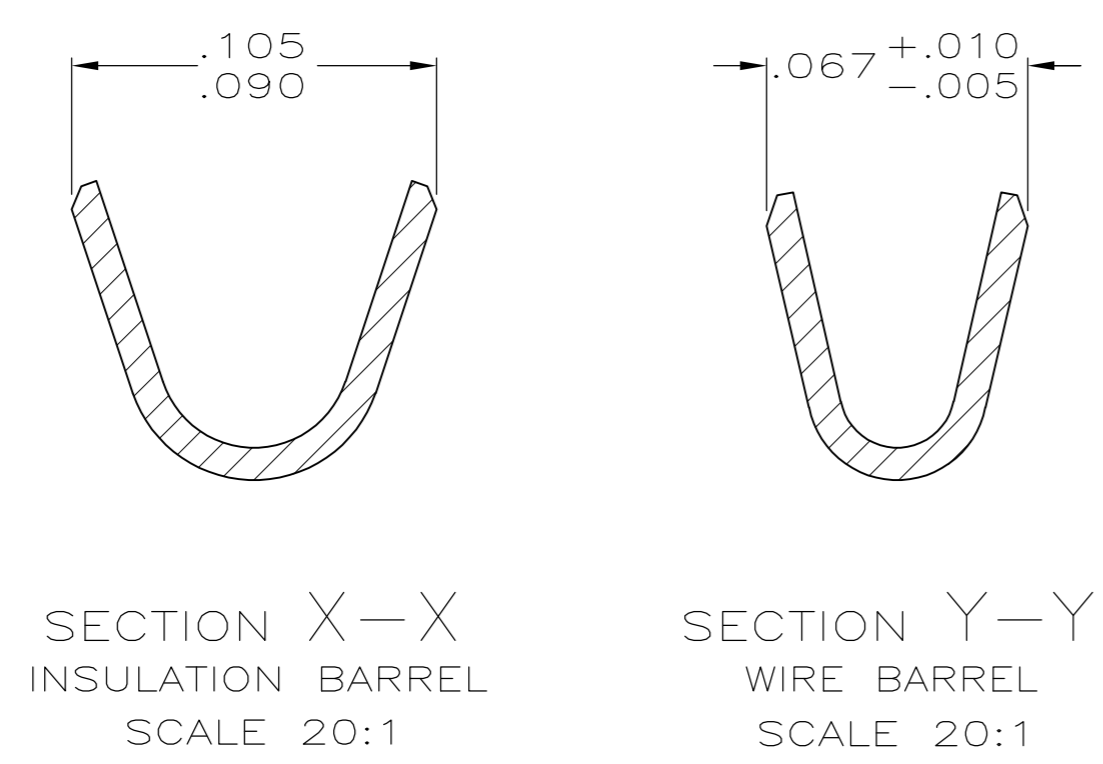


THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION
 © COPYRIGHT - By - ALL RIGHTS RESERVED.

LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION		DATE	DWN	APVD	
GP	00	L	REVISED PER ECO-12-021696	27FEB2013	CJV	SLB	



- 1 FOR MINI-APPLICATOR.
- 2 FOR HAND TOOL USE ONLY.
- 3. WIRE RANGE OF 22-26, INSULATION RANGE OF .040-.050.
- 4. GOLD PLATING MAY NOT APPEAR ON CARRIER STRIP. NICKEL UNDERPLATE COVERS ENTIRE CONTACT.
- 5 GOLD PLATING PER MIL-G-45204. NICKEL PLATING PER QQ-N-290. TIN PLATING PER MIL-T-10727.
- 6 GOLD PLATED IN LOCALIZED GOLD PLATE AREA AS FOLLOWS: .000030 MIN GOLD IN MATED AREA, GOLD FLASH ON REMAINDER OF LOCALIZED GOLD PLATE AREA AND ZONE 1 OF CONTACT, ALL OVER .000050 MIN NICKEL UNDERPLATE.
OR
GOLD FLASH OVER PALLADIUM-NICKEL PLATE, .000030 MIN TOTAL IN MATED AREA, GOLD FLASH ON REMAINDER OF LOCALIZED GOLD PLATE AREA AND ZONE 1 OF CONTACT, ALL OVER .000050 MIN NICKEL UNDERPLATE.
- 7 .000001 MIN GOLD ON LOCALIZED GOLD PLATE AREA AND ZONE 1 OVER .000030 MIN NICKEL.
- 8 GOLD PLATED IN LOCALIZED GOLD PLATED AREA, .000001 MIN GOLD IN MATED AREA, TIN PLATED WIRE BARRELS, OVER .000030 NICKEL.
- 9 GOLD PLATED IN LOCALIZED GOLD PLATED AREA, .000030 GOLD IN MATED AREA, TIN PLATED WIRE BARRELS, OVER .000050 NICKEL.



OBSELETE	SMALL PACK	7	2	LOOSE PIECE	1-745254-7
OBSELETE	STANDARD	9	2	LOOSE PIECE	1-745254-6
OBSELETE	STANDARD	9	1	STRIP	1-745254-4
OBSELETE	STANDARD	8	2	LOOSE PIECE	1-745254-3
OBSELETE	STANDARD	8	1	STRIP	1-745254-1
	STANDARD	7	2	LOOSE PIECE	745254-7
	STANDARD	6	2	LOOSE PIECE	745254-6
	STANDARD	7	1	STRIP	745254-3
	STANDARD	6	1	STRIP	745254-2
PACKAGING TYPE		FINISH	USE	TYPE	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009

DWN S.WELDON 9-9-86
 CHK C.RICHARD 9-9-86
 APVD V. KUMAR 9-10-86
 PRODUCT SPEC
 APPLICATION SPEC 114-10000
 MATERIAL BRASS PER MIL-C-50
 FINISH SEE TABLE

TE Connectivity
 PIN CONTACT, SIZE 20 DF, 22-26 AWG, W/.040-.050 DIA INSULATION SUPPORT

SIZE A2 CAGE CODE 00779 DRAWING NO C-745254 RESTRICTED TO
 SCALE 10:1 SHEET 1 of 1 REV L